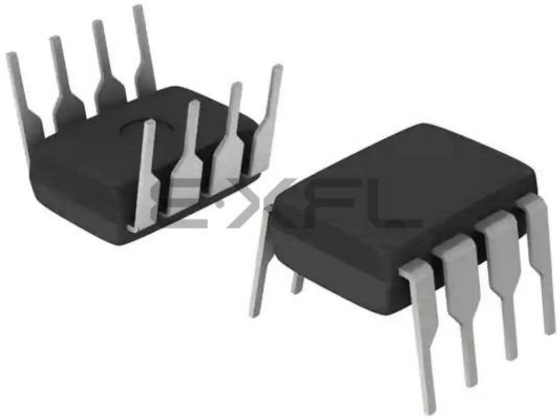
Microchip Technology - ATTINY25-20PU Datasheet



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What is "Embedded - Microcontrollers"?

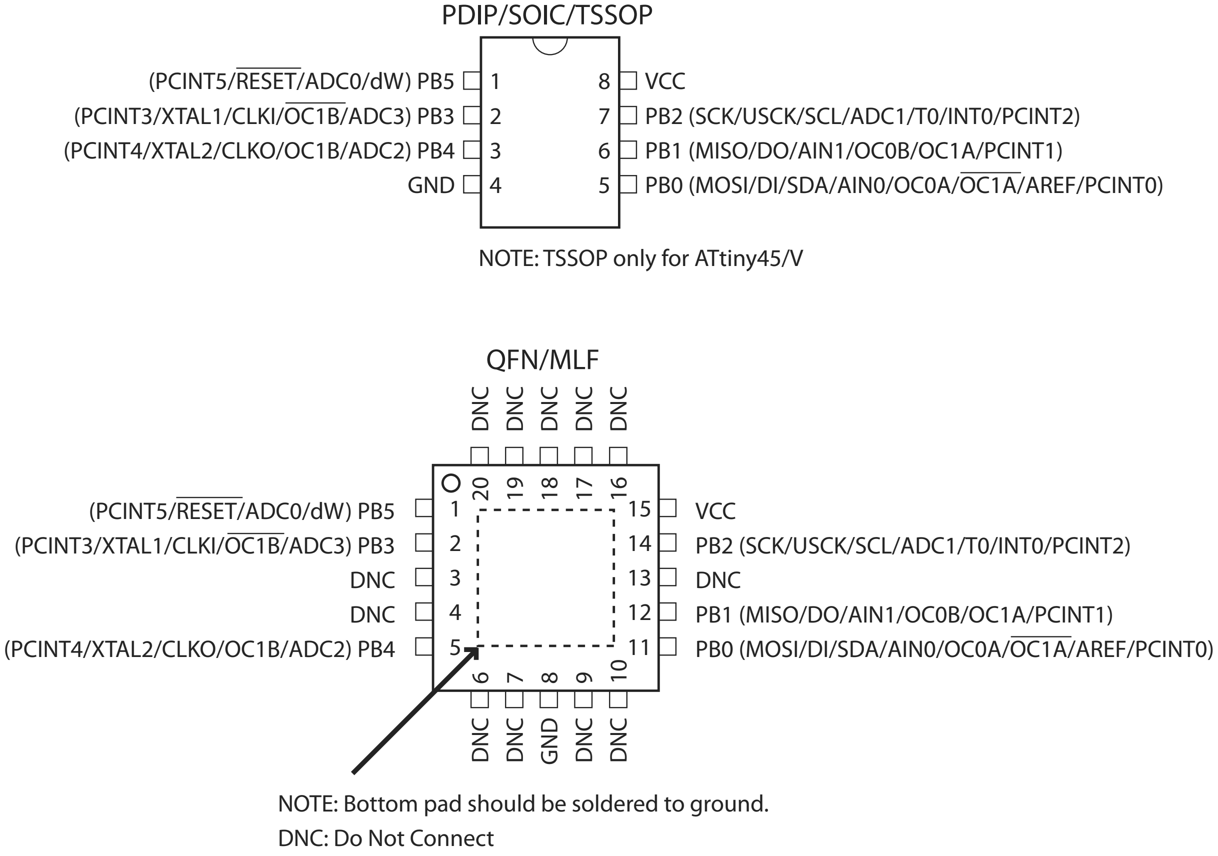
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	AVR
Core Size	8-Bit
Speed	20MHz
Connectivity	USI
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	6
Program Memory Size	2KB (1K x 16)
Program Memory Type	FLASH
EEPROM Size	128 x 8
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 4x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	8-DIP (0.300", 7.62mm)
Supplier Device Package	8-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/attiny25-20pu

1. Pin Configurations

Figure 1-1. Pinout ATtiny25/45/85



NOTE: TSSOP only for ATtiny45/V

NOTE: Bottom pad should be soldered to ground.
DNC: Do Not Connect

1.1 Pin Descriptions

1.1.1 VCC

Supply voltage.

1.1.2 GND

Ground.

1.1.3 Port B (PB5:PB0)

Port B is a 6-bit bi-directional I/O port with internal pull-up resistors (selected for each bit). The Port B output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port B pins that are externally pulled low will source current if the pull-up resistors are activated. The Port B pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Port B also serves the functions of various special features of the ATtiny25/45/85 as listed in “Alternate Functions of Port B” on page 60.

On ATtiny25, the programmable I/O ports PB3 and PB4 (pins 2 and 3) are exchanged in ATtiny15 Compatibility Mode for supporting the backward compatibility with ATtiny15.

1.1.4 $\overline{\text{RESET}}$

Reset input. A low level on this pin for longer than the minimum pulse length will generate a reset, even if the clock is not running and provided the reset pin has not been disabled. The minimum pulse length is given in Table 21-4 on page 165. Shorter pulses are not guaranteed to generate a reset.

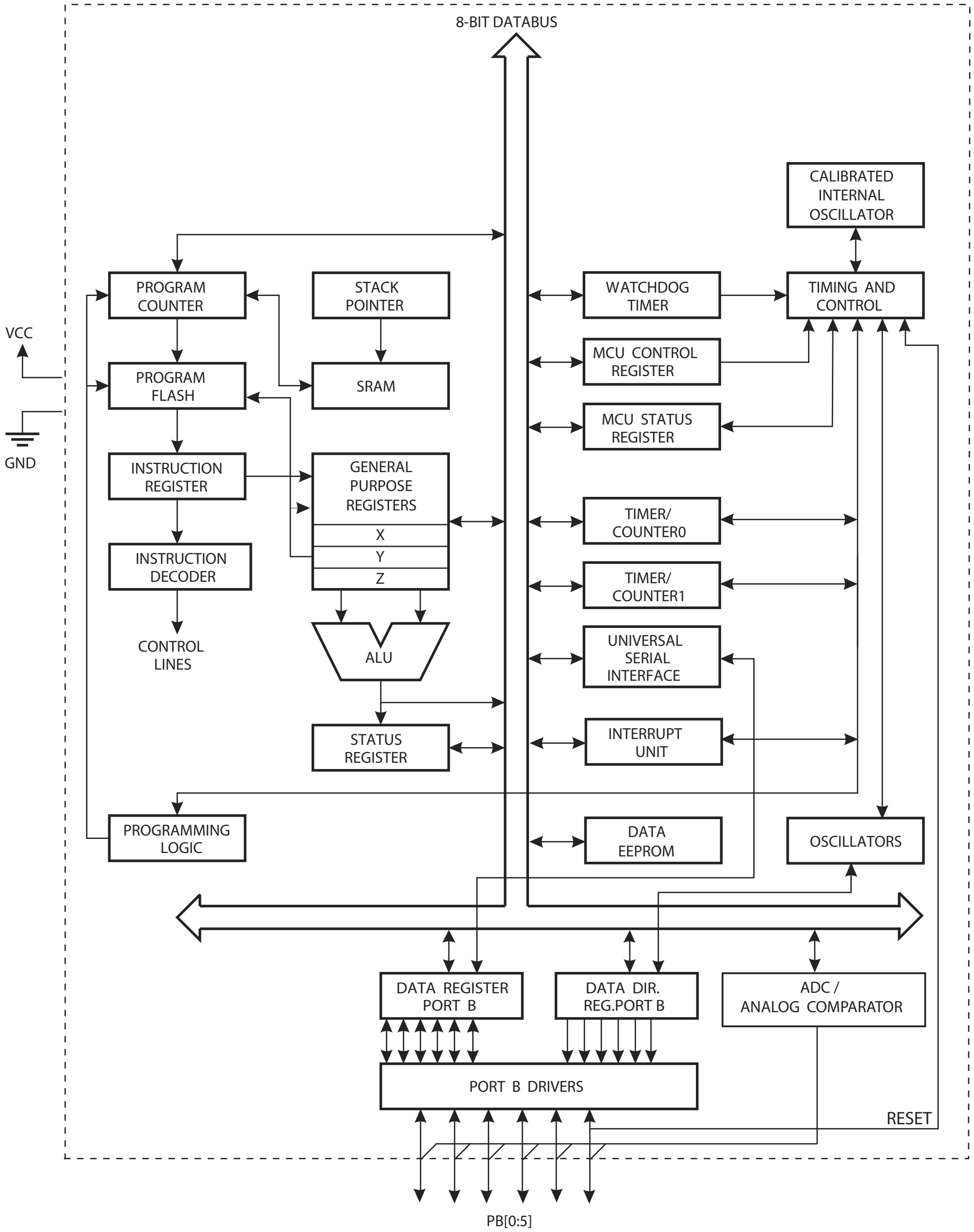
The reset pin can also be used as a (weak) I/O pin.

2. Overview

The ATtiny25/45/85 is a low-power CMOS 8-bit microcontroller based on the AVR enhanced RISC architecture. By executing powerful instructions in a single clock cycle, the ATtiny25/45/85 achieves throughputs approaching 1 MIPS per MHz allowing the system designer to optimize power consumption versus processing speed.

2.1 Block Diagram

Figure 2-1. Block Diagram



The AVR core combines a rich instruction set with 32 general purpose working registers. All 32 registers are directly connected to the Arithmetic Logic Unit (ALU), allowing two independent registers to be accessed in one single instruction executed in one clock cycle. The resulting architecture is more code efficient while achieving throughputs up to ten times faster than conventional CISC microcontrollers.

3. About

3.1 Resources

A comprehensive set of development tools, application notes and datasheets are available for download on http://www.atmel.com/avr.

3.2 Code Examples

This documentation contains simple code examples that briefly show how to use various parts of the device. These code examples assume that the part specific header file is included before compilation. Be aware that not all C compiler vendors include bit definitions in the header files and interrupt handling in C is compiler dependent. Please confirm with the C compiler documentation for more details.

For I/O Registers located in the extended I/O map, “IN”, “OUT”, “SBIS”, “SBIC”, “CBI”, and “SBI” instructions must be replaced with instructions that allow access to extended I/O. Typically, this means “LDS” and “STS” combined with “SBRS”, “SBRC”, “SBR”, and “CBR”. Note that not all AVR devices include an extended I/O map.

3.3 Capacitive Touch Sensing

Atmel QTouch Library provides a simple to use solution for touch sensitive interfaces on Atmel AVR microcontrollers. The QTouch Library includes support for QTouch® and QMatrix® acquisition methods.

Touch sensing is easily added to any application by linking the QTouch Library and using the Application Programming Interface (API) of the library to define the touch channels and sensors. The application then calls the API to retrieve channel information and determine the state of the touch sensor.

The QTouch Library is free and can be downloaded from the Atmel website. For more information and details of implementation, refer to the QTouch Library User Guide – also available from the Atmel website.

3.4 Data Retention

Reliability Qualification results show that the projected data retention failure rate is much less than 1 PPM over 20 years at 85°C or 100 years at 25°C.

should never be written.

2. I/O Registers within the address range 0x00 - 0x1F are directly bit-accessible using the SBI and CBI instructions. In these registers, the value of single bits can be checked by using the SBIS and SBIC instructions.
3. Some of the Status Flags are cleared by writing a logical one to them. Note that, unlike most other AVRs, the CBI and SBI instructions will only operation the specified bit, and can therefore be used on registers containing such Status Flags. The CBI and SBI instructions work with registers 0x00 to 0x1F only.

Mnemonics	Operands	Description	Operation	Flags	#Clocks
SWAP	Rd	Swap Nibbles	Rd(3..0)←Rd(7..4),Rd(7..4)←Rd(3..0)	None	1
BSET	s	Flag Set	SREG(s) ← 1	SREG(s)	1
BCLR	s	Flag Clear	SREG(s) ← 0	SREG(s)	1
BST	Rr, b	Bit Store from Register to T	T ← Rr(b)	T	1
BLD	Rd, b	Bit load from T to Register	Rd(b) ← T	None	1
SEC		Set Carry	C ← 1	C	1
CLC		Clear Carry	C ← 0	C	1
SEN		Set Negative Flag	N ← 1	N	1
CLN		Clear Negative Flag	N ← 0	N	1
SEZ		Set Zero Flag	Z ← 1	Z	1
CLZ		Clear Zero Flag	Z ← 0	Z	1
SEI		Global Interrupt Enable	I ← 1	I	1
CLI		Global Interrupt Disable	I ← 0	I	1
SES		Set Signed Test Flag	S ← 1	S	1
CLS		Clear Signed Test Flag	S ← 0	S	1
SEV		Set Twos Complement Overflow.	V ← 1	V	1
CLV		Clear Twos Complement Overflow	V ← 0	V	1
SET		Set T in SREG	T ← 1	T	1
CLT		Clear T in SREG	T ← 0	T	1
SEH		Set Half Carry Flag in SREG	H ← 1	H	1
CLH		Clear Half Carry Flag in SREG	H ← 0	H	1
DATA TRANSFER INSTRUCTIONS					
MOV	Rd, Rr	Move Between Registers	Rd ← Rr	None	1
MOVW	Rd, Rr	Copy Register Word	Rd+1:Rd ← Rr+1:Rr	None	1
LDI	Rd, K	Load Immediate	Rd ← K	None	1
LD	Rd, X	Load Indirect	Rd ← (X)	None	2
LD	Rd, X+	Load Indirect and Post-Inc.	Rd ← (X), X ← X + 1	None	2
LD	Rd, - X	Load Indirect and Pre-Dec.	X ← X - 1, Rd ← (X)	None	2
LD	Rd, Y	Load Indirect	Rd ← (Y)	None	2
LD	Rd, Y+	Load Indirect and Post-Inc.	Rd ← (Y), Y ← Y + 1	None	2
LD	Rd, - Y	Load Indirect and Pre-Dec.	Y ← Y - 1, Rd ← (Y)	None	2
LDD	Rd,Y+q	Load Indirect with Displacement	Rd ← (Y + q)	None	2
LD	Rd, Z	Load Indirect	Rd ← (Z)	None	2
LD	Rd, Z+	Load Indirect and Post-Inc.	Rd ← (Z), Z ← Z+1	None	2
LD	Rd, -Z	Load Indirect and Pre-Dec.	Z ← Z - 1, Rd ← (Z)	None	2
LDD	Rd, Z+q	Load Indirect with Displacement	Rd ← (Z + q)	None	2
LDS	Rd, k	Load Direct from SRAM	Rd ← (k)	None	2
ST	X, Rr	Store Indirect	(X) ← Rr	None	2
ST	X+, Rr	Store Indirect and Post-Inc.	(X) ← Rr, X ← X + 1	None	2
ST	- X, Rr	Store Indirect and Pre-Dec.	X ← X - 1, (X) ← Rr	None	2
ST	Y, Rr	Store Indirect	(Y) ← Rr	None	2
ST	Y+, Rr	Store Indirect and Post-Inc.	(Y) ← Rr, Y ← Y + 1	None	2
ST	- Y, Rr	Store Indirect and Pre-Dec.	Y ← Y - 1, (Y) ← Rr	None	2
STD	Y+q,Rr	Store Indirect with Displacement	(Y + q) ← Rr	None	2
ST	Z, Rr	Store Indirect	(Z) ← Rr	None	2
ST	Z+, Rr	Store Indirect and Post-Inc.	(Z) ← Rr, Z ← Z + 1	None	2
ST	-Z, Rr	Store Indirect and Pre-Dec.	Z ← Z - 1, (Z) ← Rr	None	2
STD	Z+q,Rr	Store Indirect with Displacement	(Z + q) ← Rr	None	2
STS	k, Rr	Store Direct to SRAM	(k) ← Rr	None	2
LPM		Load Program Memory	R0 ← (Z)	None	3
LPM	Rd, Z	Load Program Memory	Rd ← (Z)	None	3
LPM	Rd, Z+	Load Program Memory and Post-Inc	Rd ← (Z), Z ← Z+1	None	3
SPM		Store Program Memory	(z) ← R1:R0	None	
IN	Rd, P	In Port	Rd ← P	None	1
OUT	P, Rr	Out Port	P ← Rr	None	1
PUSH	Rr	Push Register on Stack	STACK ← Rr	None	2
POP	Rd	Pop Register from Stack	Rd ← STACK	None	2
MCU CONTROL INSTRUCTIONS					
NOP		No Operation		None	1
SLEEP		Sleep	(see specific descr. for Sleep function)	None	1
WDR		Watchdog Reset	(see specific descr. for WDR/Timer)	None	1
BREAK		Break	For On-chip Debug Only	None	N/A

6.2 ATtiny45

Speed (MHz) [1]	Supply Voltage (V)	Temperature Range	Package [2]	Ordering Code [3]
10	1.8 – 5.5	Industrial (-40°C to +85°C) [4]	8P3	ATtiny45V-10PU
			8S2	ATtiny45V-10SU ATtiny45V-10SUR ATtiny45V-10SH ATtiny45V-10SHR
			8X	ATtiny45V-10XU ATtiny45V-10XUR
			20M1	ATtiny45V-10MU ATtiny45V-10MUR
20	2.7 – 5.5	Industrial (-40°C to +85°C) [4]	8P3	ATtiny45-20PU
			8S2	ATtiny45-20SU ATtiny45-20SUR ATtiny45-20SH ATtiny45-20SHR
			8X	ATtiny45-20XU ATtiny45-20XUR
			20M1	ATtiny45-20MU ATtiny45-20MUR

Notes:

1. For speed vs. supply voltage, see section 21.3 “Speed” on page 163.
2. All packages are Pb-free, halide-free and fully green and they comply with the European directive for Restriction of Hazardous Substances (RoHS).
3. Code indicators:
   - H: NiPdAu lead finish
   - U: matte tin
   - R: tape & reel
4. These devices can also be supplied in wafer form. Please contact your local Atmel sales office for detailed ordering information and minimum quantities.

Package Types	
8P3	8-lead, 0.300" Wide, Plastic Dual Inline Package (PDIP)
8S2	8-lead, 0.208" Wide, Plastic Gull-Wing Small Outline (EIAJ SOIC)
8X	8-lead, 4.4 mm Wide, Plastic Thin Shrink Small Outline Package (TSSOP)
20M1	20-pad, 4 x 4 x 0.8 mm Body, Quad Flat No-Lead/Micro Lead Frame Package (QFN/MLF)

6.3 ATtiny85

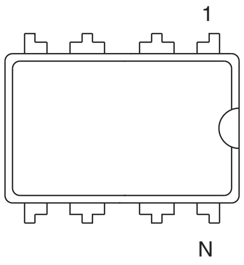
Speed (MHz) [1]	**Supply Voltage (V)**	**Temperature Range**	**Package** [2]	**Ordering Code** [3]
10	1.8 – 5.5	Industrial (-40°C to +85°C) [4]	8P3	ATtiny85V-10PU
			8S2	ATtiny85V-10SU ATtiny85V-10SUR ATtiny85V-10SH ATtiny85V-10SHR
			20M1	ATtiny85V-10MU ATtiny85V-10MUR
20	2.7 – 5.5	Industrial (-40°C to +85°C) [4]	8P3	ATtiny85-20PU
			8S2	ATtiny85-20SU ATtiny85-20SUR ATtiny85-20SH ATtiny85-20SHR
			20M1	ATtiny85-20MU ATtiny85-20MUR

Notes:
1. For speed vs. supply voltage, see section 21.3 “Speed” on page 163.
2. All packages are Pb-free, halide-free and fully green and they comply with the European directive for Restriction of Hazardous Substances (RoHS).
3. Code indicators:
   - H: NiPdAu lead finish
   - U: matte tin
   - R: tape & reel
4. These devices can also be supplied in wafer form. Please contact your local Atmel sales office for detailed ordering information and minimum quantities.

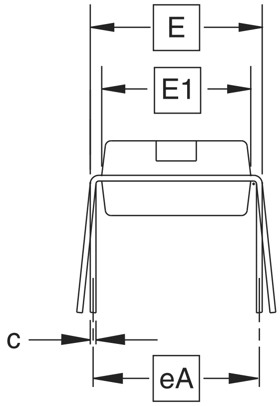
Package Types	
8P3	8-lead, 0.300" Wide, Plastic Dual Inline Package (PDIP)
8S2	8-lead, 0.208" Wide, Plastic Gull-Wing Small Outline (EIAJ SOIC)
20M1	20-pad, 4 x 4 x 0.8 mm Body, Quad Flat No-Lead/Micro Lead Frame Package (QFN/MLF)

7. Packaging Information

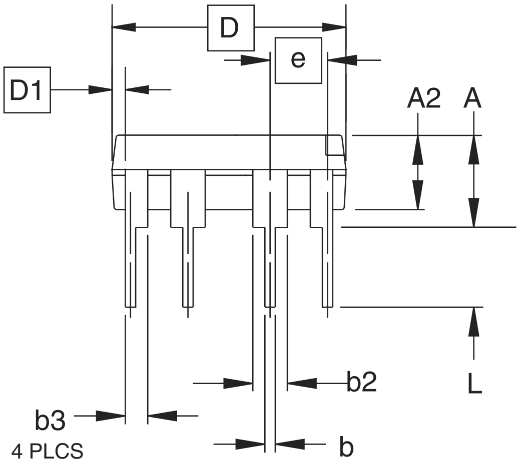
7.1 8P3



Top View



End View



Side View

COMMON DIMENSIONS

(Unit of Measure = inches)

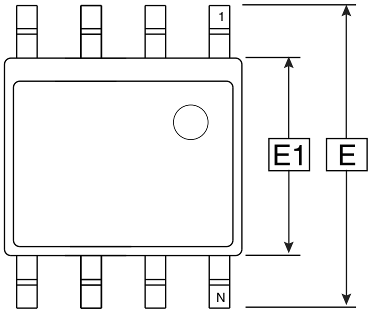
SYMBOL	MIN	NOM	MAX	NOTE
A			0.210	2
A2	0.115	0.130	0.195	
b	0.014	0.018	0.022	5
b2	0.045	0.060	0.070	6
b3	0.030	0.039	0.045	6
c	0.008	0.010	0.014	
D	0.355	0.365	0.400	3
D1	0.005			3
E	0.300	0.310	0.325	4
E1	0.240	0.250	0.280	3
e	0.100 BSC			
eA	0.300 BSC			4
L	0.115	0.130	0.150	2

Notes:
1. This drawing is for general information only; refer to JEDEC Drawing MS-001, Variation BA for additional information.
2. Dimensions A and L are measured with the package seated in JEDEC seating plane Gauge GS-3.
3. D, D1 and E1 dimensions do not include mold Flash or protrusions. Mold Flash or protrusions shall not exceed 0.010 inch.
4. E and eA measured with the leads constrained to be perpendicular to datum.
5. Pointed or rounded lead tips are preferred to ease insertion.
6. b2 and b3 maximum dimensions do not include Dambar protrusions. Dambar protrusions shall not exceed 0.010 (0.25 mm).

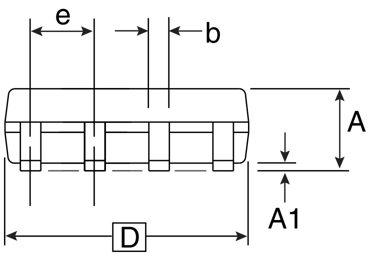
01/09/02

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**8P3**, 8-lead, 0.300" Wide Body, Plastic Dual In-line Package (PDIP)	8P3	B

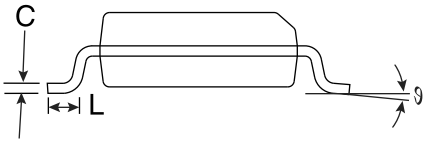
7.3 S8S1



Top View



Side View



End View

COMMON DIMENSIONS
(Unit of Measure = mm)

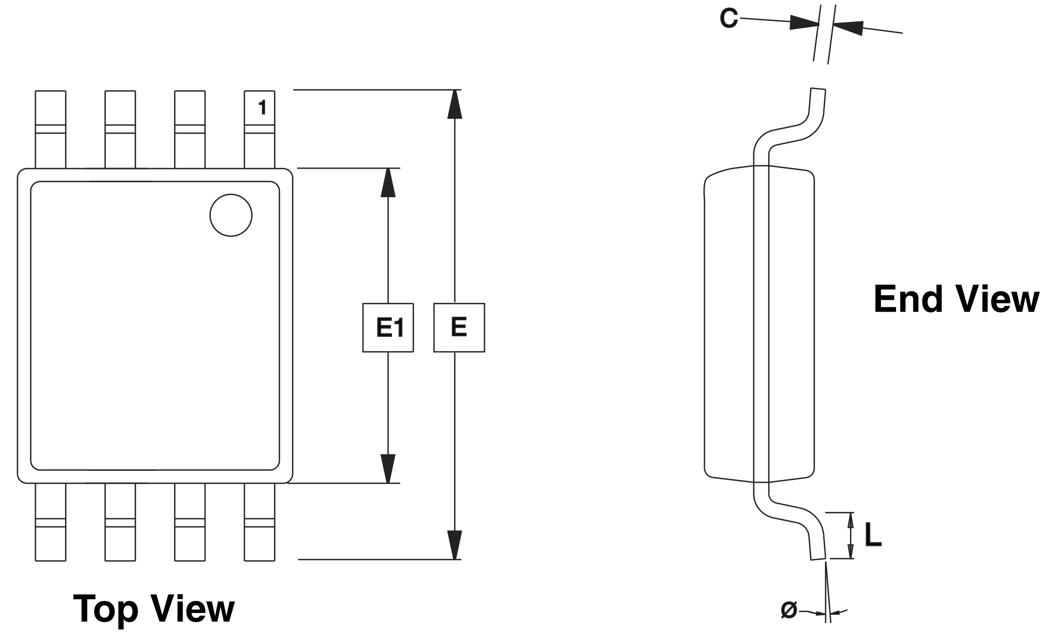
SYMBOL	MIN	NOM	MAX	NOTE
E	5.79		6.20	
E1	3.81		3.99	
A	1.35		1.75	
A1	0.1		0.25	
D	4.80		4.98	
C	0.17		0.25	
b	0.31		0.51	
L	0.4		1.27	
e	1.27 BSC			
ϑ	0°		8°	

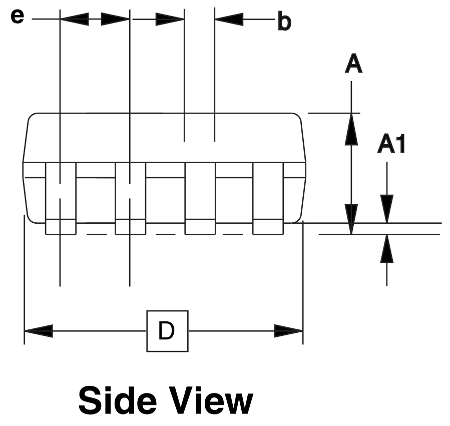
Notes: 1. This drawing is for general information only; refer to JEDEC Drawing MS-012 for proper dimensions, tolerances, datums,etc.

7/28/03

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**S8S1**, 8-lead, 0.150" Wide Body, Plastic Gull Wing Small Outline (JEDEC SOIC)	S8S1	A

7.4 8X





COMMON DIMENSIONS
(Unit of Measure = mm)

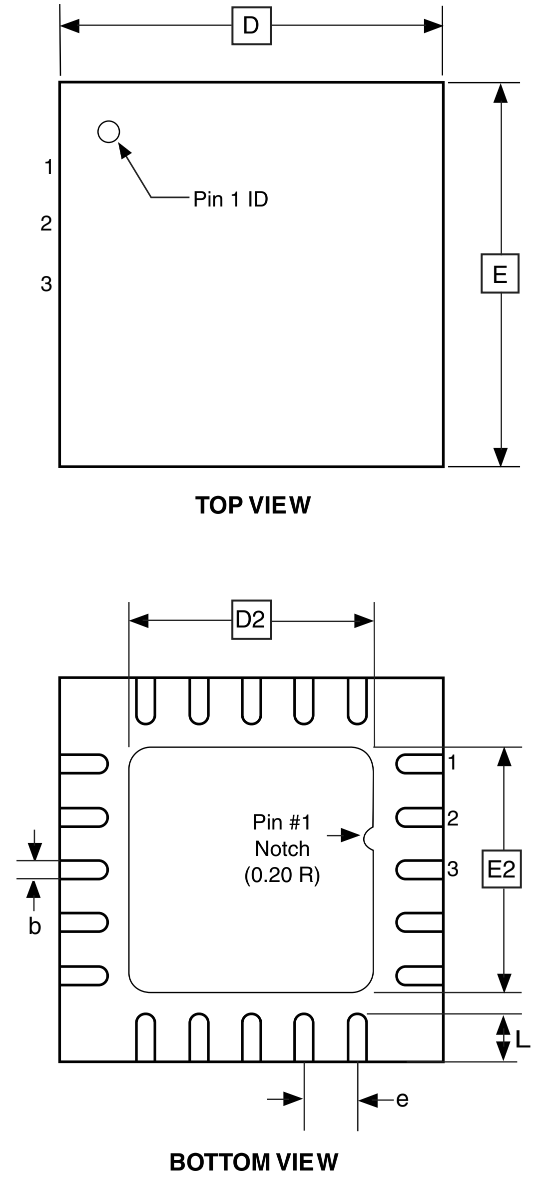
SYMBOL	MIN	NOM	MAX	NOTE
A	1.05	1.10	1.20	
A1	0.05	0.10	0.15	
b	0.25	–	0.30	
C	–	0.127	–	
D	2.90	3.05	3.10	
E1	4.30	4.40	4.50	
E	6.20	6.40	6.60	
e	0.65 TYP			
L	0.50	0.60	0.70	
ø	0°	–	8°	

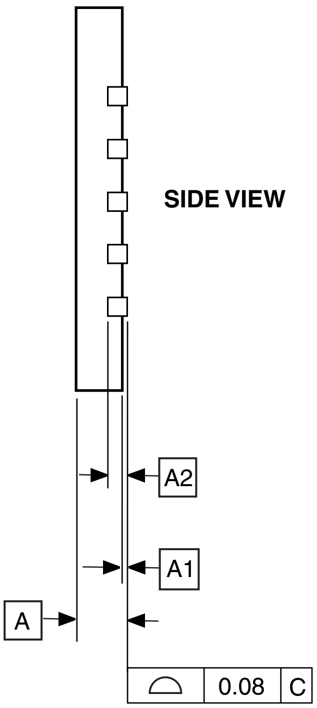
Note: These drawings are for general information only. Refer to JEDEC Drawing MO-153AC.

4/14/05

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**8X**, 8-lead, 4.4 mm Body Width, Plastic Thin Shrink Small Outline Package (TSSOP)	8X	A

7.5 20M1





Note: Reference JEDEC Standard MO-220, Fig. 1 (SAW Singulation) WGGD-5.

COMMON DIMENSIONS
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	0.70	0.75	0.80	
A1	–	0.01	0.05	
A2		0.20 REF		
b	0.18	0.23	0.30	
D		4.00 BSC		
D2	2.45	2.60	2.75	
E		4.00 BSC		
E2	2.45	2.60	2.75	
e		0.50 BSC		
L	0.35	0.40	0.55	

10/27/04

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**20M1**, 20-pad, 4 x 4 x 0.8 mm Body, Lead Pitch 0.50 mm, 2.6 mm Exposed Pad, Micro Lead Frame Package (MLF)	20M1	B

8. Errata

8.1 Errata ATtiny25

The revision letter in this section refers to the revision of the ATtiny25 device.

8.1.1 Rev D – F

No known errata.

8.1.2 Rev B – C

- **EEPROM read may fail at low supply voltage / low clock frequency**

1. **EEPROM read may fail at low supply voltage / low clock frequency**

   Trying to read EEPROM at low clock frequencies and/or low supply voltage may result in invalid data.

   Problem Fix/Workaround

   Do not use the EEPROM when clock frequency is below 1MHz and supply voltage is below 2V. If operating frequency can not be raised above 1MHz then supply voltage should be more than 2V. Similarly, if supply voltage can not be raised above 2V then operating frequency should be more than 1MHz.

   This feature is known to be temperature dependent but it has not been characterised. Guidelines are given for room temperature, only.

8.1.3 Rev A

Not sampled.

8.2 Errata ATtiny45

The revision letter in this section refers to the revision of the ATtiny45 device.

8.2.1 Rev F – G

No known errata

8.2.2 Rev D – E

- **EEPROM read may fail at low supply voltage / low clock frequency**

1. **EEPROM read may fail at low supply voltage / low clock frequency**

   Trying to read EEPROM at low clock frequencies and/or low supply voltage may result in invalid data.

   Problem Fix/Workaround

   Do not use the EEPROM when clock frequency is below 1MHz and supply voltage is below 2V. If operating frequency can not be raised above 1MHz then supply voltage should be more than 2V. Similarly, if supply voltage can not be raised above 2V then operating frequency should be more than 1MHz.

   This feature is known to be temperature dependent but it has not been characterised. Guidelines are given for room temperature, only.

8.2.3 Rev B – C

- **PLL not locking**
- **EEPROM read from application code does not work in Lock Bit Mode 3**
- **EEPROM read may fail at low supply voltage / low clock frequency**
- **Timer Counter 1 PWM output generation on OC1B- XOC1B does not work correctly**

1. **PLL not locking**

   When at frequencies below 6.0 MHz, the PLL will not lock

   Problem fix / Workaround

   When using the PLL, run at 6.0 MHz or higher.

2. **EEPROM read from application code does not work in Lock Bit Mode 3**

   When the Memory Lock Bits LB2 and LB1 are programmed to mode 3, EEPROM read does not work from the application code.

   Problem Fix/Work around

   Do not set Lock Bit Protection Mode 3 when the application code needs to read from EEPROM.

3. **EEPROM read may fail at low supply voltage / low clock frequency**

   Trying to read EEPROM at low clock frequencies and/or low supply voltage may result in invalid data.

   Problem Fix/Workaround

   Do not use the EEPROM when clock frequency is below 1MHz and supply voltage is below 2V. If operating frequency can not be raised above 1MHz then supply voltage should be more than 2V. Similarly, if supply voltage can not be raised above 2V then operating frequency should be more than 1MHz.

   This feature is known to be temperature dependent but it has not been characterised. Guidelines are given for room temperature, only.

4. **Timer Counter 1 PWM output generation on OC1B – XOC1B does not work correctly**

   Timer Counter1 PWM output OC1B-XOC1B does not work correctly. Only in the case when the control bits, COM1B1 and COM1B0 are in the same mode as COM1A1 and COM1A0, respectively, the OC1B-XOC1B output works correctly.

   Problem Fix/Work around

   The only workaround is to use same control setting on COM1A[1:0] and COM1B[1:0] control bits, see table 14-4 in the data sheet. The problem has been fixed for Tiny45 rev D.

8.2.4 Rev A

- **Too high power down power consumption**
- **DebugWIRE looses communication when single stepping into interrupts**
- **PLL not locking**
- **EEPROM read from application code does not work in Lock Bit Mode 3**
- **EEPROM read may fail at low supply voltage / low clock frequency**

1. **Too high power down power consumption**

   Three situations will lead to a too high power down power consumption. These are:

   - An external clock is selected by fuses, but the I/O PORT is still enabled as an output.
   - The EEPROM is read before entering power down.
   - VCC is 4.5 volts or higher.

   Problem fix / Workaround

8.3 Errata ATtiny85

The revision letter in this section refers to the revision of the ATtiny85 device.

8.3.1 Rev B – C

No known errata.

8.3.2 Rev A

- **EEPROM read may fail at low supply voltage / low clock frequency**

1. **EEPROM read may fail at low supply voltage / low clock frequency**

   Trying to read EEPROM at low clock frequencies and/or low supply voltage may result in invalid data.

   Problem Fix/Workaround

   Do not use the EEPROM when clock frequency is below 1MHz and supply voltage is below 2V. If operating frequency can not be raised above 1MHz then supply voltage should be more than 2V. Similarly, if supply voltage can not be raised above 2V then operating frequency should be more than 1MHz.

   This feature is known to be temperature dependent but it has not been characterised. Guidelines are given for room temperature, only.

  - Tape & reel part numbers in Ordering Information, in Section 6.1 “ATtiny25” on page 11 and Section 6.2 “ATtiny45” on page 12
2. Updated:
  - “Features” on page 1, removed Preliminary from ATtiny25
  - Section 8.4.2 “Code Example” on page 44
  - “PCMSK – Pin Change Mask Register” on page 52, Bit Descriptions
  - “TCCR1 – Timer/Counter1 Control Register” on page 89 and “GTCCR – General Timer/Counter1 Control Register” on page 90, COM bit descriptions clarified
  - Section 20.3.2 “Calibration Bytes” on page 150, frequencies (8 MHz, 6.4 MHz)
  - Table 20-11, “Minimum Wait Delay Before Writing the Next Flash or EEPROM Location,” on page 153, value for t_{WD_ERASE}
  - Table 20-16, “High-voltage Serial Programming Instruction Set for ATtiny25/45/85,” on page 158
  - Table 21-1, “DC Characteristics. T_A = -40°C to +85°C,” on page 161, notes adjusted
  - Table 21-11, “Serial Programming Characteristics, T_A = -40°C to +85°C, V_{CC} = 1.8 - 5.5V (Unless Otherwise Noted),” on page 170, added t_{SLIV}
  - Bit syntax throughout the datasheet, e.g. from CS02:0 to CS0[2:0].

9.7 Rev. 2586K-01/08

1. Updated Document Template.
2. Added Sections:
  - “Data Retention” on page 6
  - “Low Level Interrupt” on page 49
  - “Device Signature Imprint Table” on page 149
3. Updated Sections:
  - “Internal PLL for Fast Peripheral Clock Generation - clkPCK” on page 24
  - “System Clock and Clock Options” on page 23
  - “Internal PLL in ATtiny15 Compatibility Mode” on page 24
  - “Sleep Modes” on page 34
  - “Software BOD Disable” on page 35
  - “External Interrupts” on page 49
  - “Timer/Counter1 in PWM Mode” on page 97
  - “USI – Universal Serial Interface” on page 108
  - “Temperature Measurement” on page 133
  - “Reading Lock, Fuse and Signature Data from Software” on page 143
  - “Program And Data Memory Lock Bits” on page 147
  - “Fuse Bytes” on page 148
  - “Signature Bytes” on page 150
  - “Calibration Bytes” on page 150
  - “System and Reset Characteristics” on page 165
4. Added Figures:
  - “Reset Pin Output Voltage vs. Sink Current (V_{CC} = 3V)” on page 184
  - “Reset Pin Output Voltage vs. Sink Current (V_{CC} = 5V)” on page 185
  - “Reset Pin Output Voltage vs. Source Current (V_{CC} = 3V)” on page 185

9.9 Rev. 2586I-09/06

1. All Characterization data moved to “Electrical Characteristics” on page 161.
2. All Register Descriptions are gathered up in seperate sections in the end of each chapter.
3. Updated Table 11-3 on page 78, Table 11-5 on page 79, Table 11-6 on page 80 and Table 20-4 on page 148.
4. Updated “Calibrated Internal Oscillator” on page 27.
5. Updated Note in Table 7-1 on page 34.
6. Updated “System Control and Reset” on page 39.
7. Updated Register Description in “I/O Ports” on page 53.
8. Updated Features in “USI – Universal Serial Interface” on page 108.
9. Updated Code Example in “SPI Master Operation Example” on page 110 and “SPI Slave Operation Example” on page 111.
10. Updated “Analog Comparator Multiplexed Input” on page 119.
11. Updated Figure 17-1 on page 123.
12. Updated “Signature Bytes” on page 150.
13. Updated “Electrical Characteristics” on page 161.

9.10 Rev. 2586H-06/06

1. Updated “Calibrated Internal Oscillator” on page 27.
2. Updated Table 6.5.1 on page 31.
3. Added Table 21-2 on page 164.

9.11 Rev. 2586G-05/06

1. Updated “Internal PLL for Fast Peripheral Clock Generation - clkPCK” on page 24.
2. Updated “Default Clock Source” on page 30.
3. Updated “Low-Frequency Crystal Oscillator” on page 29.
4. Updated “Calibrated Internal Oscillator” on page 27.
5. Updated “Clock Output Buffer” on page 31.
6. Updated “Power Management and Sleep Modes” on page 34.
7. Added “Software BOD Disable” on page 35.
8. Updated Figure 16-1 on page 119.
9. Updated “Bit 6 – ACBG: Analog Comparator Bandgap Select” on page 120.
10. Added note for Table 17-2 on page 125.
11. Updated “Register Summary” on page 7.

9.12 Rev. 2586F-04/06

1. Updated “Digital Input Enable and Sleep Modes” on page 57.
2. Updated Table 20-16 on page 158.
3. Updated “Ordering Information” on page 11.

9.13 Rev. 2586E-03/06

1. Updated Features in “Analog to Digital Converter” on page 122.
2. Updated Operation in “Analog to Digital Converter” on page 122.
3. Updated Table 17-2 on page 133.
4. Updated Table 17-3 on page 134.
5. Updated “Errata” on page 19.

9.14 Rev. 2586D-02/06

1. Updated Table 6-13 on page 30, Table 6-10 on page 29, Table 6-3 on page 26, Table 6-9 on page 28, Table 6-5 on page 26, Table 9-1 on page 48,Table 17-4 on page 135, Table 20-16 on page 158, Table 21-8 on page 167.
2. Updated “Timer/Counter1 in PWM Mode” on page 86.
3. Updated text “Bit 2 – TOV1: Timer/Counter1 Overflow Flag” on page 93.
4. Updated values in “DC Characteristics” on page 161.
5. Updated “Register Summary” on page 7.
6. Updated “Ordering Information” on page 11.
7. Updated Rev B and C in “Errata ATtiny45” on page 19.
8. All references to power-save mode are removed.
9. Updated Register Adresses.

9.15 Rev. 2586C-06/05

1. Updated “Features” on page 1.
2. Updated Figure 1-1 on page 2.
3. Updated Code Examples on page 18 and page 19.
4. Moved “Temperature Measurement” to Section 17.12 page 133.
5. Updated “Register Summary” on page 7.
6. Updated “Ordering Information” on page 11.

9.16 Rev. 2586B-05/05

1. CLKI added, instances of EEMWE/EEWE renamed EEMPE/EEPE, removed some TBD.
   Removed “Preliminary Description” from “Temperature Measurement” on page 133.
2. Updated “Features” on page 1.
3. Updated Figure 1-1 on page 2 and Figure 8-1 on page 39.
4. Updated Table 7-2 on page 38, Table 10-4 on page 63, Table 10-5 on page 63
5. Updated “Serial Programming Instruction set” on page 153.
6. Updated SPH register in “Instruction Set Summary” on page 9.
7. Updated “DC Characteristics” on page 161.
8. Updated “Ordering Information” on page 11.
9. Updated “Errata” on page 19.

9.17 Rev. 2586A-02/05

Initial revision.

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